

#13  
Starn / Amended  
c**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. .... 10/004,172  
Filing Date ..... October 9, 2001  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-1839  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding  
Frames

**RESPONSE TO FEBRUARY 11, 2003 OFFICE ACTION**  
**and APRIL 24, 2003 NOTICE OF NON-COMPLIANT AMENDMENT**

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

From: D. Brent Kenady  
Tel. 509-624-4276; Fax 509-838-3424  
Wells St. John P.S.  
601 West First Avenue, Suite 1300  
Spokane, WA 99201-3828

**RECEIVED****MAY 9 2003****Group 3700**

Responsive to the Office Action dated February 11, 2003 and the Notice of Non-Compliant Amendment dated April 24, 2003, Applicant amends and remarks as follows:

**AMENDMENTS**